

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: H. NAKAMURA, et al.  
Serial No.: 10/500,119  
Filed: JUNE 17, 2005  
For: CONNECTION BOARD, AND MULTI-LAYER WIRING BOARD,  
SUBSTRATE FOR SEMICONDUCTOR PACKAGE AND  
SEMICONDUCTOR PACKAGE USING CONNECTION  
BOARD, AND MANUFACTURING METHOD THEREOF  
Group AU: 2841  
Examiner: Ishwarbhai B Patel  
Confirm. No: 7910

**RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT**

**Mail Stop: AMEND – NO FEE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

January 14, 2008

Sir:

In response to the Notice of Non-compliant Amendment mailed December 12, 2007, please replace the “**Amendments to the Claims**” section of the Amendment filed October 11, 2007, with the following “**Amendments to the Claims**” section.